Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method of refining a surface of a printed circuit board, the method comprising:

(a) providing a brush comprising:

(i) a plurality of bristles integrally molded with a central portion of the brush, the bristles comprising thermoplastic polymer, polysiloxane lubricant, and silicon carbide abrasive particles, the thermoplastic polymer having a Shore D hardness of 55-90;

(ii) the plurality of bristles having a length of 0.0625 inch to 1.5 inch;

(b) contacting the brush with the surface of a printed circuit board comprising a copper surface and having apertures therethrough;

(c) refining the surface to provide a copper surface having ~~an acceptable~~ a surface finish of 0.05 to 0.3 micrometer Ra ~~and to provide acceptable apertures~~.

2. (Original) The method according to claim 1, wherein the step of providing a brush comprises:

(a) providing a brush comprising a plurality of bristles having a length of 0.25 inch to 0.5 inch.

3. (Original) The method according to claim 1, wherein the step of providing a brush comprises:

(a) providing a brush having bristles comprising a thermoplastic polymer having a Shore D hardness of 70-85.

4. (Original) The method according to claim 1, wherein the step of providing a brush comprises:

(a) providing a brush having bristles comprising 2-20 wt-% polysiloxane lubricant.

5. (Original) The method according to claim 4, wherein the step of providing a brush comprises:

(a) providing a brush having bristles comprising 5-15 wt-% polysiloxane lubricant.

6. (Original) The method according to claim 1, wherein the step of providing a brush comprises:

(a) providing a brush having bristles comprising 20-45 wt-% silicon carbide particles.

7. (Original) The method according to claim 1, wherein the step of providing a brush comprises:

(a) providing a brush having bristles with a cross-section 0.01 to 0.05 inch wide and 0.01 to 0.05 inch high.

8. (Original) The method according to claim 7, wherein the step of providing a brush comprises:

(a) providing a brush having bristles with a cross-section 0.025 inch wide and 0.025 inch high.

9. (Currently Amended) The method according to claim 1, wherein the step of providing a brush comprises:

(a) providing a brush having ~~trapezoidal~~ bristles with a cross-section that is a trapezoid.

10. (Cancelled)

11. (Currently Amended) The method according to claim ~~10~~ 1, wherein the step of refining the surface comprises:

(a) refining the surface to provide a surface finish of 0.1 to 0.2 micrometer Ra.

12. (Original) The method according to claim 1, wherein the step of refining the surface comprises:

(a) refining the surface to provide unplugged apertures.

13. (Original) The method according to claim 1, wherein the step of contacting the brush with the surface of a printed circuit board comprises:

(a) contacting the brush with the surface of the printed circuit board to create a footprint that is 1.25% to 2.75% of a circumference of the brush with a 150 mm wide contact width.

14. (New) A method of refining a surface of a printed circuit board, the method comprising:

(a) providing a brush comprising:

(i) a plurality of bristles integrally molded with a central portion of the brush, the bristles comprising thermoplastic polymer, polysiloxane lubricant, and silicon carbide abrasive particles, the thermoplastic polymer having a Shore D hardness of 55-90;

(ii) the plurality of bristles having a length of 0.0625 inch to 1.5 inch;

(b) contacting the brush with the surface of a printed circuit board comprising a copper surface and having apertures therethrough;

(c) refining the surface to provide a copper surface having a finish with unplugged

apertures.

15. (New) The method according to claim 14, wherein refining the surface further comprises refining the surface to provide a copper surface having a surface finish of 0.05 to 0.3 micrometer Ra.

16. (New) A method of refining a surface of a printed circuit board, the method comprising:

(a) providing a brush comprising:

(i) a plurality of bristles integrally molded with a central portion of the brush, the bristles comprising thermoplastic polymer, polysiloxane lubricant, and silicon carbide abrasive particles, the thermoplastic polymer having a Shore D hardness of 55-90;

(ii) the plurality of bristles having a length of 0.0625 inch to 1.5 inch;

(b) contacting the brush with the surface of a printed circuit board comprising a copper surface and having apertures therethrough, wherein contacting the brush with the surface of the printed circuit board creates a footprint that is 1.25% to 2.75% of a circumference of the brush.

17. (New) The method of claim 16, further comprising refining the surface to provide a copper surface having a surface finish of 0.05 to 0.3 micrometer Ra and with unplugged apertures.